

# Semi-rigid (with solid dielectric) Cable

## Cable Type 70 (421-669-1)

Cut-off Frequency: 33.00 GHz

| General   |               |
|---|---------------|
| Cable Model No.   | 421-669-1     |
| Cable Code for Cable Assemblies                                     | 70            |
| Cable MIL-C17 No.   | None          |
| Cut-off Frequency (GHz)   | 33.00         |
| Electrical  |               |
| Impedance<br>(Ohms @ sea level and +25°C)                           | 50 ± 1        |
| Velocity of Propagation<br>(in %, ±2 %)                             | 69.50         |
| Capacitance (in pF/m)   | 95.10         |
| Dielectric Strength<br>(KV <sub>rms</sub> @ 60 Hz)                  | 5.00          |
| Max. Operating Voltage<br>(KV <sub>rms</sub> @ 60 Hz and sea level) | 1.90          |
| Mechanical  |               |
| Semi-rigid Type<br>(Dia. in inches)                                 | 0.141         |
| Outer Conductor<br>(Dia. in mm)                                     | 3.60          |
| Outer Conductor Material  | copper        |
| Outer Conductor Finish  | silver-plated |
| Dielectric<br>(Dia. in mm)  | 2.98          |
| Dielectric Material   | solid PTFE    |
| Dielectric Constant   | ~2.0          |
| Center Conductor Material   | Steel         |
| Center Conductor Finish   | silver-plated |
| Center Conductor<br>(Dia. in mm)                                    | 0.93          |
| Weight<br>(grams/m)   | 51.20         |
| Minimum Bend Radius,<br>Inside, Static (mm)                         | 6.35          |
| Environmental   |               |
| Operating Temperature Range<br>(°C)                                 | -54 to +125   |

### Characteristics:

### Additional Information:

- [Connector Code details](#)
- [Information on armor](#)
- [Ordering Information](#)

### Comparison of regular PTFE and low-density PTFE:

|  | Regular PTFE Dielectric | Low-density Dielectric  |
|--|-------------------------|---|
| Mechanical Stability vs. Temperature       | Poor                    | Good<br>Lower coefficient of thermal expansion results in improved dimensional stability from -100°C to +250°C. |
| Phase Stability vs. Temperature            | Poor                    | Good<br>Lower coefficient of thermal expansion results in lower Phase Shift vs. Temperature.                    |
| Change in Propagation Time vs. Temperature | Poor                    | Improved<br>The change in propagation time 70 - 80% less than when using solid PTFE.                            |

|                |        |  |
|----------------|--------|--|
| Attenuation    | Higher | Lower<br>Lower dissipation factor of the dielectric, lower dielectric constant, larger center conductor result in lower attenuation. |
| Power Handling | Lower  | Higher<br>Good temperature stability allows higher operating temperature, and therefore higher power.                                |
| Weight         | Higher | Lower<br>Low density dielectric results in lower weight.   |

### Attenuation & Power Graph:

